

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Chad A. Cobbley et. al

Serial No.: 10/771,243

Filed: February 3, 2004

STACKED DIE MODULE AND
TECHNIQUES FOR FORMING A
STACKED DIE MODULE

§ Group Art Unit: 2823
§
§ Confirmation No.: 2594
§
§ Examiner: Parker, John M.
§
§ Atty. Docket:
§ MICS:0078-4/FLE/MAN/TOM
§ 01-0752.04

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37 C.F.R. 1.8

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August 12, 2008	/Robert A. Manware/
Date	Robert A. Manware

Sir:

**RESPONSE TO
FINAL OFFICE ACTION MAILED JUNE 12, 2008**

In response to the Office Action mailed on June 12, 2008, Applicants respectfully request reconsideration of the above-identified application in view of the remarks set forth below.